

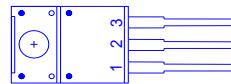
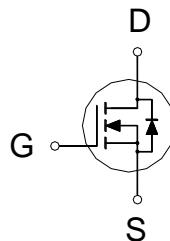
NIKO-SEM
**N-Channel Enhancement Mode
Field Effect Transistor**
P1065ETF

TO-220F

Halogen-Free & Lead-Free

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
650V	0.77Ω	10A

**ABSOLUTE MAXIMUM RATINGS($T_A=25^\circ\text{C}$ Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	650	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ²	I_D	10	A
		6	
Pulsed Drain Current ¹	I_{DM}	35	
Avalanche Current ³	I_{AS}	5	
Avalanche Energy ³	E_{AS}	125	mJ
Power Dissipation	P_D	48	W
		19	
Operating Junction & Storage Temperature Range	T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.6	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	°C / W

¹Pulse width limited by maximum junction temperature.²Ensure that the channel temperature does not exceed 150°C.³ $V_{DD} = 50\text{V}$, $L = 10\text{mH}$, starting $T_J = 25^\circ\text{C}$.**ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}$, $I_D = 250\mu\text{A}$	650			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	2	2.8	4	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{V}$, $V_{GS} = \pm 30\text{V}$			± 100	nA

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Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 650V, V_{GS} = 0V, T_C = 25^{\circ}C$			1	μA
		$V_{DS} = 520V, V_{GS} = 0V, T_C = 100^{\circ}C$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 5A$		0.55	0.77	Ω
Forward Transconductance ¹	g_{fs}	$V_{DS} = 10V, I_D = 5A$		18		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		2017		pF
Output Capacitance	C_{oss}			167		
Reverse Transfer Capacitance	C_{rss}			9		
Total Gate Charge ²	Q_g	$V_{DD} = 520V, I_D = 10A, V_{GS} = 10V$		44		nC
Gate-Source Charge ²	Q_{gs}			13		
Gate-Drain Charge ²	Q_{gd}			8.5		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DD} = 325V, I_D = 10A, R_G = 25\Omega$		33		nS
Rise Time ²	t_r			38		
Turn-Off Delay Time ²	$t_{d(off)}$			136		
Fall Time ²	t_f			71		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^{\circ}C$)						
Continuous Current ³	I_S				10	A
Forward Voltage ¹	V_{SD}	$I_F = 10A, V_{GS} = 0V$			1	V
Reverse Recovery Time	t_{rr}	$I_F = 10A, dI_F/dt = 100A/\mu S$		451		nS
Reverse Recovery Charge	Q_{rr}			5.8		uC

¹Pulse test : Pulse Width $\leq 380 \mu sec$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

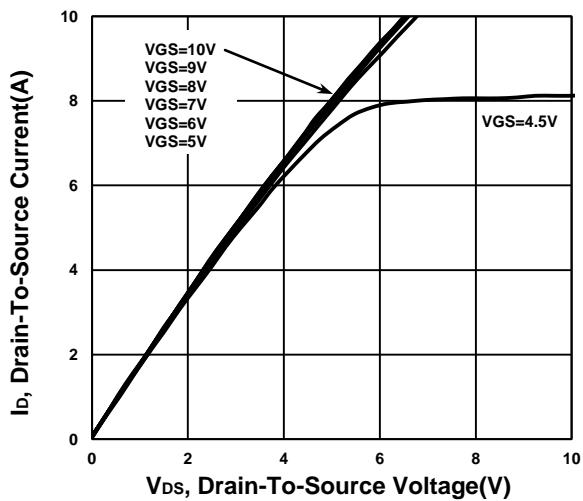
³Pulse width limited by maximum junction temperature.

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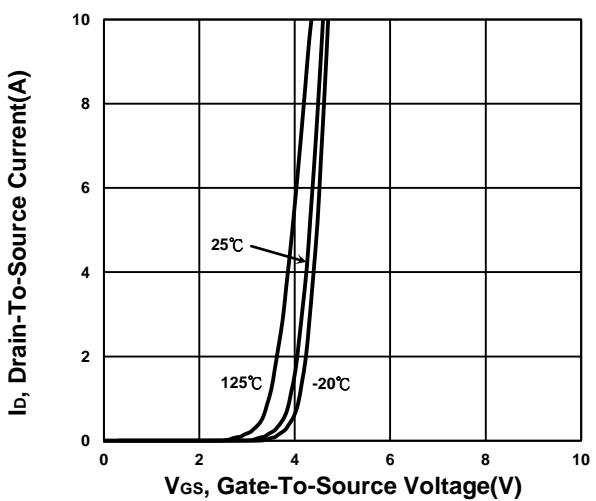
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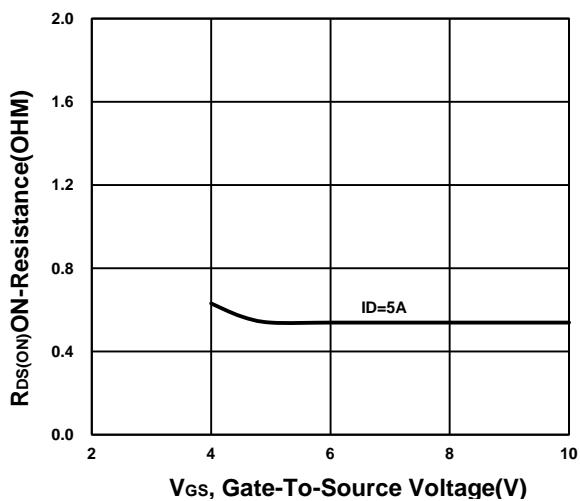
Output Characteristics



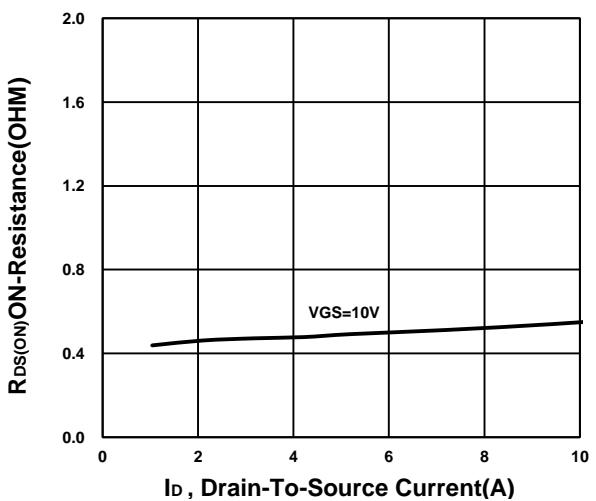
Transfer Characteristics



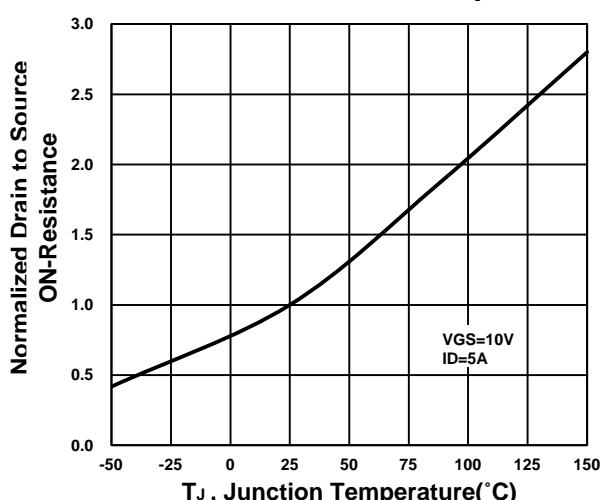
On-Resistance VS Gate-To-Source



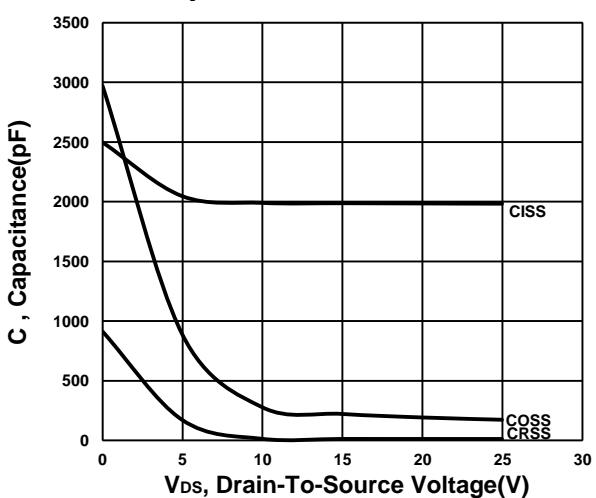
On-Resistance VS Drain Current

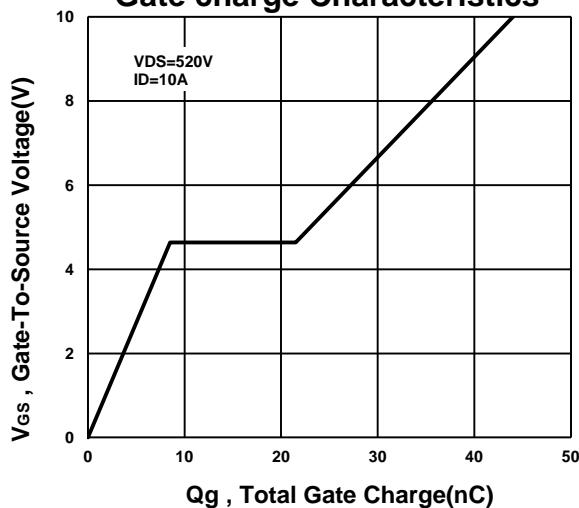
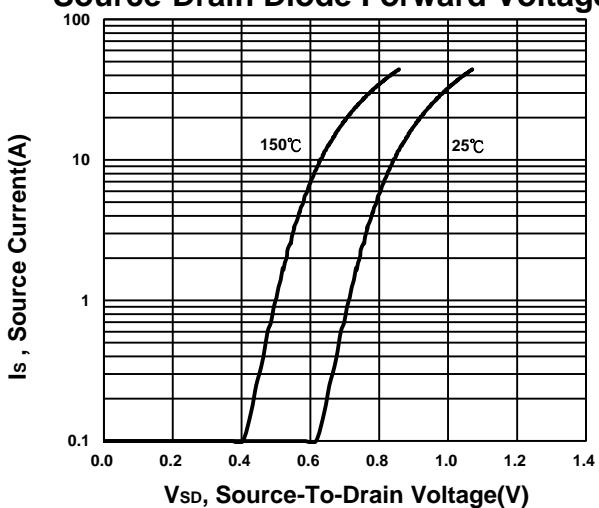
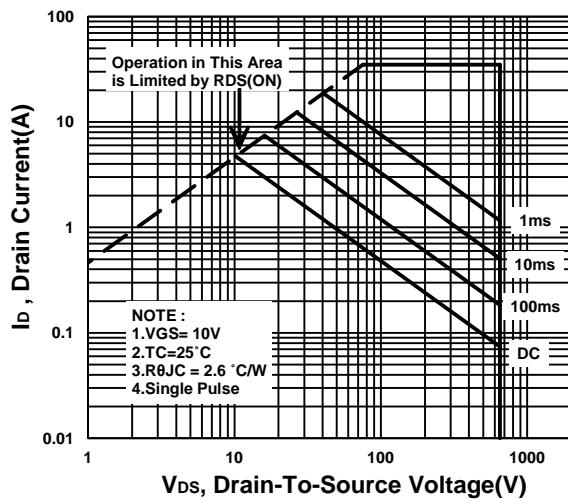
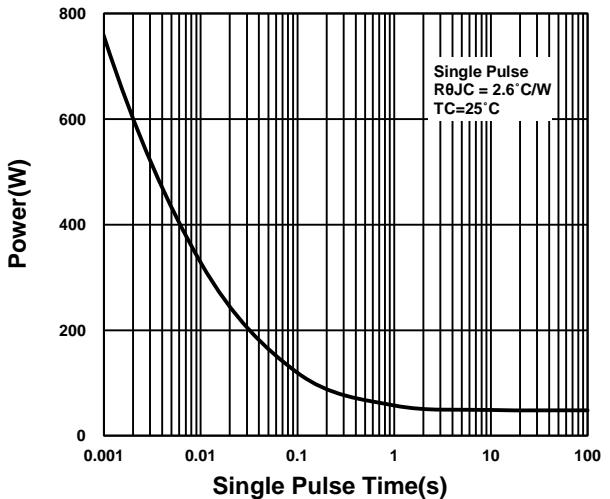


On-Resistance VS Temperature



Capacitance Characteristic



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Gate charge Characteristics**Source-Drain Diode Forward Voltage****Safe Operating Area****Single Pulse Maximum Power Dissipation****Transient Thermal Response Curve**